

Title (en)

METHOD FOR PRODUCING THREE-DIMENSIONAL, SELECTIVELY METALLIZED PARTS AND A THREE-DIMENSIONAL, SELECTIVELY METALLIZED PART

Title (de)

VERFAHREN ZUR HERSTELLUNG VON DREIDIMENSIONALEN SELEKTIV METALLISIERTEN TEILEN UND DREIDIMENSIONALES SELEKTIV METALLISIERTES TEIL

Title (fr)

PROCEDE DE FABRICATION DE PIECES TRIDIMENSIONNELLES METALLISEES DE MANIERE SELECTIVE ET PIECE TRIDIMENSIONNELLE METALLISEE DE MANIERE SELECTIVE

Publication

**EP 1287179 A2 20030305 (DE)**

Application

**EP 01943070 A 20010510**

Priority

- DE 0101824 W 20010510
- DE 10026640 A 20000529

Abstract (en)

[origin: US2001045361A1] The parts are produced by two-component injection molding. Those regions that are to be metallized consist of a first plastic and those regions that are not to be metallized consist of a second plastic. After the entire surface of the parts has been seeded, the seeding is selectively removed with the aid of a solvent in the regions which are not to be metallized. The first plastic is insoluble and the second plastic soluble in the solvent. The selective metallization then takes place by electroless metal deposition and, if appropriate, electrodeposition of metal.

IPC 1-7

**C23C 18/16**

IPC 8 full level

**B05D 1/36** (2006.01); **B05D 5/12** (2006.01); **C23C 18/06** (2006.01); **C23C 18/16** (2006.01); **C23C 18/20** (2006.01); **C23C 18/54** (2006.01); **C25D 5/00** (2006.01); **C25D 5/02** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP KR US)

**C23C 18/1608** (2013.01 - EP KR US); **C23C 18/1641** (2013.01 - EP KR US); **C23C 18/1653** (2013.01 - EP KR US); **C23C 18/30** (2013.01 - EP KR US); **H01R 12/716** (2013.01 - EP KR US); **H05K 3/182** (2013.01 - EP KR US); **Y10T 428/31678** (2015.04 - EP US); **Y10T 428/31681** (2015.04 - EP US); **Y10T 428/31696** (2015.04 - EP US)

Citation (search report)

See references of WO 0192596A2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

**US 2001045361 A1 20011129**; **US 6673227 B2 20040106**; CN 1432072 A 20030723; EP 1287179 A2 20030305; JP 2003535219 A 20031125; KR 20030007745 A 20030123; TW 514674 B 20021221; WO 0192596 A2 20011206; WO 0192596 A3 20021003

DOCDB simple family (application)

**US 83533501 A 20010416**; CN 01810398 A 20010510; DE 0101824 W 20010510; EP 01943070 A 20010510; JP 2002500785 A 20010510; KR 20027016168 A 20021128; TW 90111256 A 20010511